L Number	Hits	Search Text	DB	Time stamp
1	681	349/20-22.ccls. 349/161.ccls.	USPAT;	2004/05/04 10:45
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	1	(349/20-22.ccls. 349/161.ccls.) and (dummy adj cell)	USPAT;	2004/05/04 10:45
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	1008	heat\$3 near10 ((embed\$4 buried burying bury inside) near6	USPAT;	2004/05/04 10:45
		cell)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	20	(heat\$3 near10 ((embed\$4 buried burying bury inside) near6	USPAT;	2004/05/04 11:10
		cell)) and 349/\$.ccls.	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	2	"20020089638"	USPAT;	2004/05/04 11:20
	İ		US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	4
6	90	conductive near3 spacer near6 seal\$3	USPAT;	2004/05/04 11:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0004/05/04 44.04
7	146	conduct\$3 near3 spacer near6 seal\$3	USPAT;	2004/05/04 11:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	67	(annihitating many) annihitating	IBM_TDB   USPAT;	2004/05/04 11:22
8	67	(conduct\$3 near3 spacer near6 seal\$3) and (heat\$3 (temperature near3 control\$4))	US-PGPUB;	2004/05/04 11.22
		(temperature nears control=4))	EPO; JPO;	!
			DERWENT;	
			IBM_TDB	
9	27	((conduct\$3 near3 spacer near6 seal\$3) and (heat\$3	USPAT;	2004/05/04 12:13
] 3	21	(temperature near3 control\$4))) and (display LCD)	US-PGPUB;	2004/00/04 12:10
		(15)   Paratara hadra contrology	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	4	DSTN and heater	USPAT;	2004/05/04 12:13
,			US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
11	4	DSTN and (heating near3 element)	USPAT;	2004/05/04 12:13
		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	4	DSTN and heater	USPAT;	2004/05/04 12:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

13	7	(DSTN and (heating near3 element)) (DSTN and heater)	USPAT; US-PGPUB; EPO: JPO:	2004/05/04 12:13
			DERWENT;	

L Number	Hits	Search Text	DB	Time stamp
1	1	2000JP-0013220.ap,prai.	USPAT;	2004/05/04 14:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0004/05/04 44 00
2	934	349/\$.ccls. and ((heating near3 element) heater)	USPAT;	2004/05/04 14:20
			US-PGPUB;	·
			EPO; JPO;	
			DERWENT;	
1,	364	(240/9 cale, and (/heating near) clament) heater)) and (	IBM_TDB USPAT;	2004/05/04 14:20
3	304	(349/\$.ccls. and ((heating near3 element) heater)) and ( (plural multiple multi two three several) adj2 (layer panel	US-PGPUB:	2004/03/04 14.20
		substrate))	EPO; JPO;	
		Substitute;	DERWENT:	
			IBM TDB	
4	1136	349/\$.ccls. and ( (heating near3 (device element structure))	USPAT:	2004/05/04 14:21
'	,,,,,	heater)	US-PGPUB:	
		···-···,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	690	conduct\$3 near3 spacer same seal\$3	USPAT;	2004/05/04 14:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	7	(349/\$.ccls. and ( (heating near3 (device element structure))	USPAT;	2004/05/04 14:43
	·	heater)) and (conduct\$3 near3 spacer same seal\$3 )	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	l		IBM_TDB	